

General Description

- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge

Features

- 30V, 5.2A

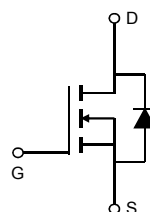
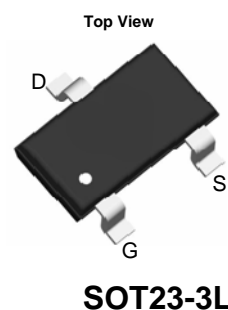
$R_{DS(ON)}$ Typ = 18.5mΩ @ $V_{GS} = 10V$

$R_{DS(ON)}$ Typ = 19.8mΩ @ $V_{GS} = 4.5V$

$R_{DS(ON)}$ Typ = 24.5mΩ @ $V_{GS} = 2.5V$

Applications

- Load Switch
- PWM Application
- Power Management



Absolute Maximum Ratings (@ $T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Units	
V _{DS}	Drain-to-Source Voltage	30	V	
V _{GS}	Gate-to-Source Voltage	±12	V	
I _D	Continuous Drain Current	T _A = 25°C	5	A
		T _A = 100°C	3.12	A
I _{DM}	Pulsed Drain Current ⁽¹⁾	20.8	A	
P _D	Power Dissipation	T _A = 25°C	1.25	W
R _{θJA}	Thermal Resistance, Junction to Ambient ⁽²⁾	100	°C/W	
T _J , T _{STG}	Junction & Storage Temperature Range	-55 to 150	°C	

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V	30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 30V, V _{GS} = 0V	-	-	1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±12V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	0.45	0.8	1.25	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽³⁾	V _{GS} = 10V, I _D = 3A	-	18.5	27	mΩ
		V _{GS} = 4.5V, I _D = 2A	-	19.8	29.5	mΩ
		V _{GS} = 2.5V, I _D = 1A	-	24.5	37	mΩ
		Dynamic Characteristics				
C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = 15V, f = 1MHz	-	505	-	pF
C _{oss}	Output Capacitance		-	48	-	pF
C _{rss}	Reverse Transfer Capacitance		-	41	-	pF
Q _g	Total Gate Charge	V _{GS} = 0 to 4.5V V _{DS} = 15V, I _D = 3A	-	7	-	nC
Q _{gs}	Gate Source Charge		-	1.7	-	nC
Q _{gd}	Gate Drain("Miller") Charge		-	1.6	-	nC
Switching Characteristics						
t _{d(on)}	Turn-On DelayTime	V _{GS} = 4.5V, V _{DD} = 15V I _D = 3A, R _{GEN} = 3Ω	-	4	-	ns
t _r	Turn-On Rise Time		-	17	-	ns
t _{d(off)}	Turn-Off DelayTime		-	95	-	ns
t _f	Turn-Off Fall Time		-	37	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current	V _{GS} = 0V, I _S = 3A	-	-	5.2	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	20.8	A
V _{SD}	Drain to Source Diode Forward Voltage		-	-	1.2	V
trr	Body Diode Reverse Recovery Time		-	6.7	-	ns
Qrr	Body Diode Reverse Recovery Charge		I _F = 3A, di/dt = 100A/us	-	2.3	-

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. $R_{\theta JA}$ is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB
 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Test Circuit

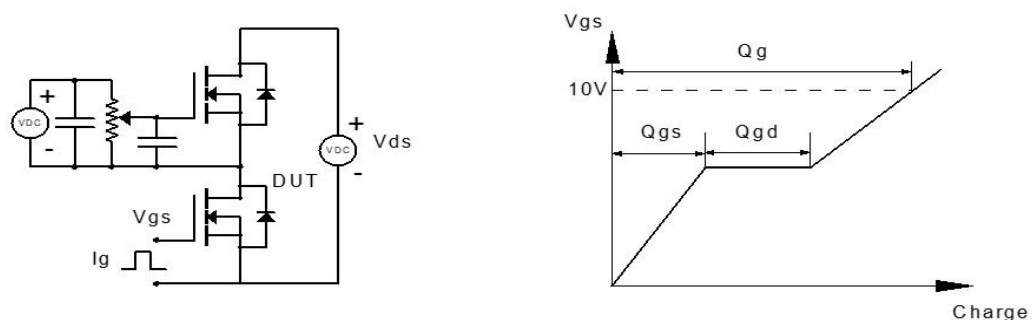


Figure 1: Gate Charge Test Circuit & Waveform

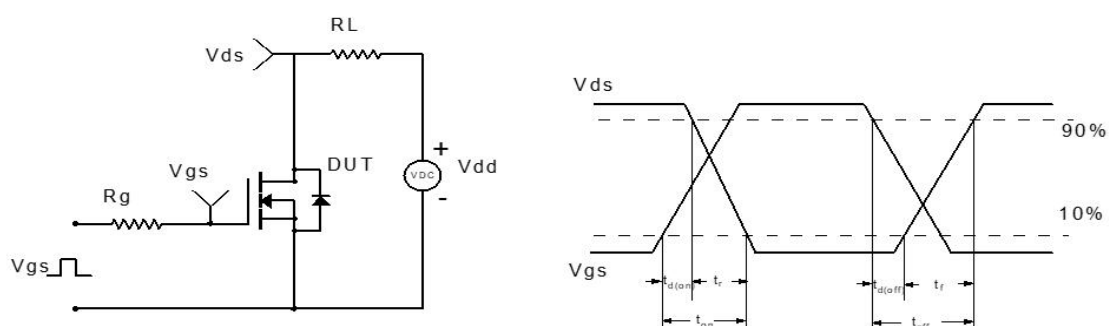


Figure 2: Resistive Switching Test Circuit & Waveform

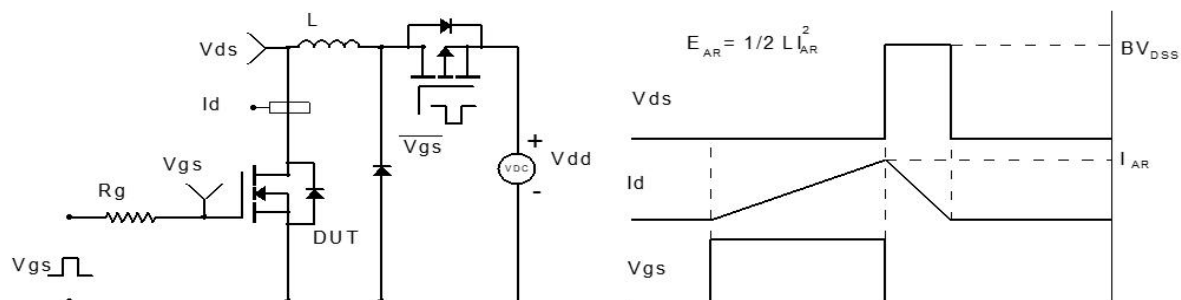


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

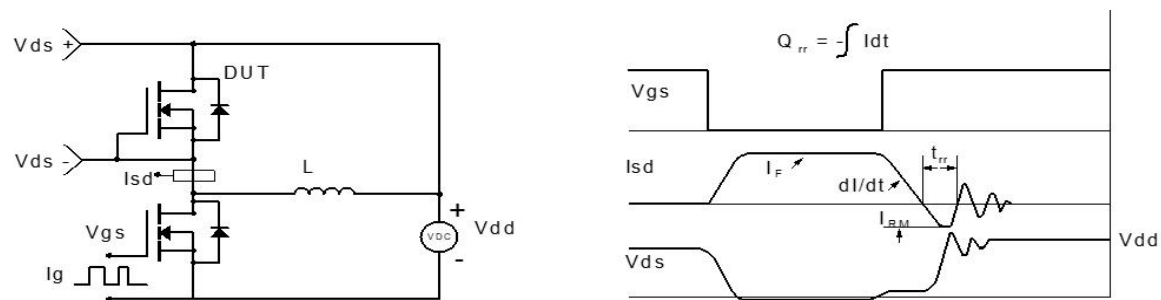
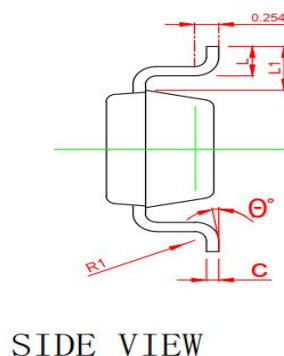
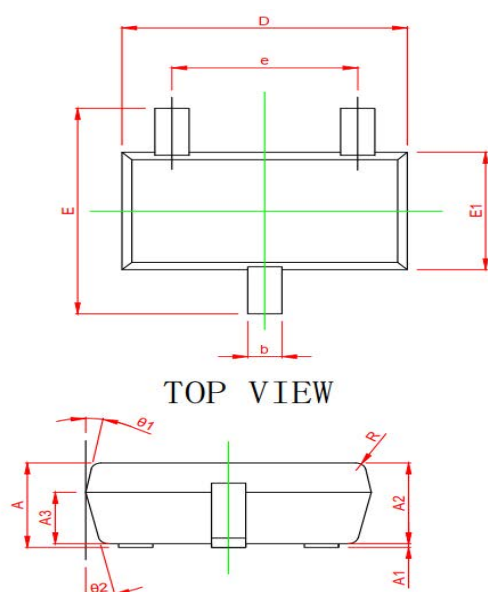


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(SOT-23-3L)



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	-	-	1.25
* A1	0.02	-	0.10
* A2	1.05	1.10	1.15
A3	0.65	0.70	0.75
* b	0.30	0.35	0.45
* c	0.127 BSC		
* D	2.87	2.92	2.97
* E	2.72	2.80	2.88
* E1	1.55	1.60	1.65
* e	1.85	1.90	1.95
* L	0.32	0.40	0.48
* L1	0.55	0.60	0.65
R	0.10 REF		
R1	0.12 REF		
* θ	0	--	8°
θ_1	8°	10°	12°
θ_2	10°	12°	14°